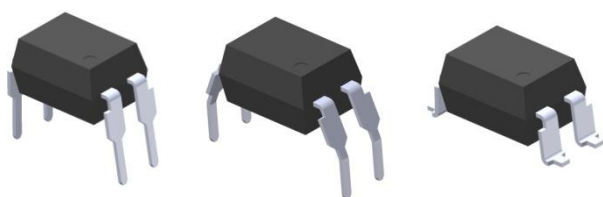
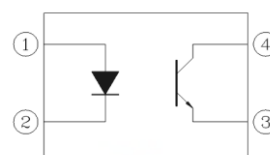


4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL817-G Series



Schematic



Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

Features:

- Compliance Halogens Free
(Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- Current transfer ratio
(CTR: 50~600% at $I_F = 5\text{mA}$, $V_{CE} = 5\text{V}$)
- High isolation voltage between input and output (Viso = 5000Vrms)
- Creepage distance > 7.62mm
- Operating temperature up to +110°C
- Compact small outline package
- Compliance with EU REACH.
- The product itself will remain within RoHS compliant version
- UL and cUL approved(No.E214129)
- VDE approved (No.132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Description

The EL817-G series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector.

They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	60	mA
	Peak forward current (1us, pulse)	I _{FP}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P _D	100	mW
	Derating factor (above T _a = 100°C)		2.9	mW/°C
Output	Power dissipation	P _C	150	mW
	Derating factor (above T _a = 100°C)		5.8	mW/°C
	Collector current	I _C	50	mA
	Collector-Emitter voltage	V _{CEO}	80	V
	Emitter-Collector voltage	V _{ECO}	7	V
Total Power Dissipation		P _{TOT}	200	mW
Isolation Voltage*1		V _{ISO}	5000	V rms
Operating Temperature		T _{OPR}	-55 to 110	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering Temperature*2		T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V _F	-	1.2	1.4	V	I _F = 20mA
Reverse Current	I _R	-	-	10	μA	V _R = 4V
Input capacitance	C _{in}	-	30	250	pF	V = 0, f = 1kHz

Output

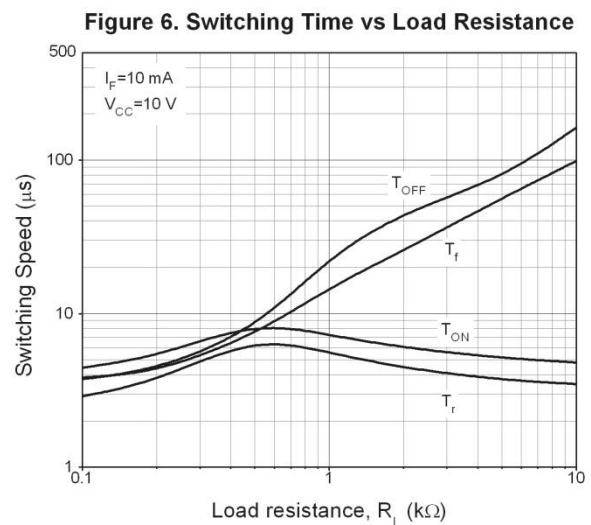
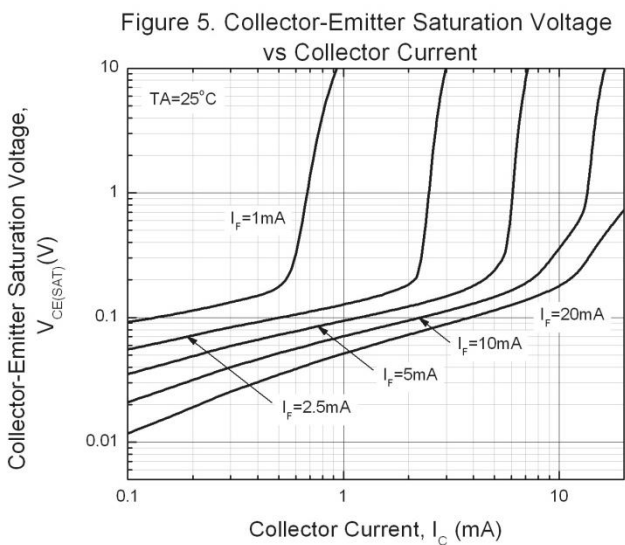
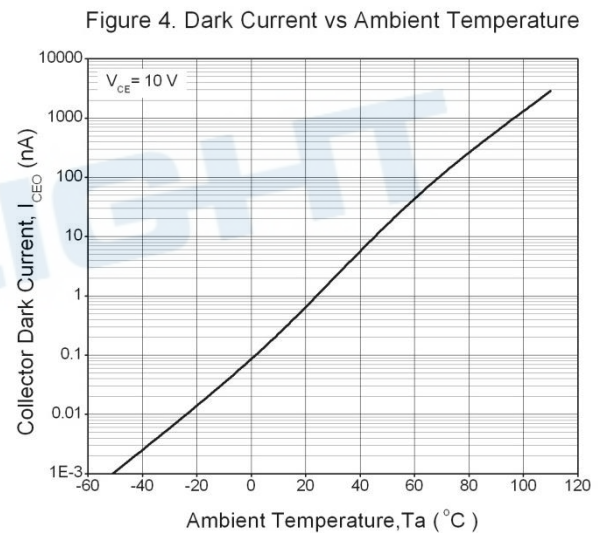
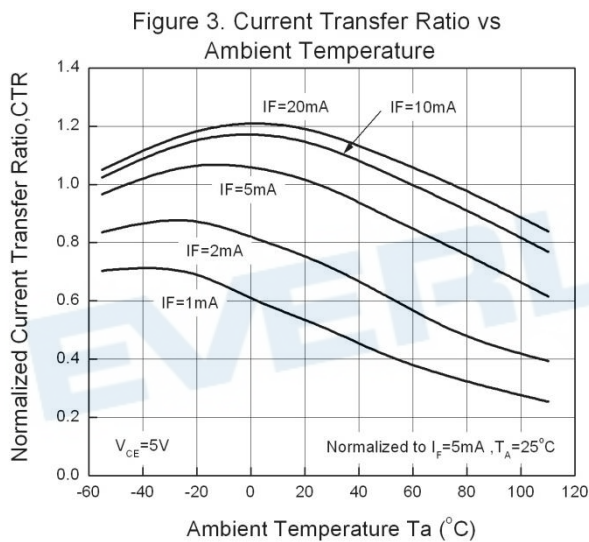
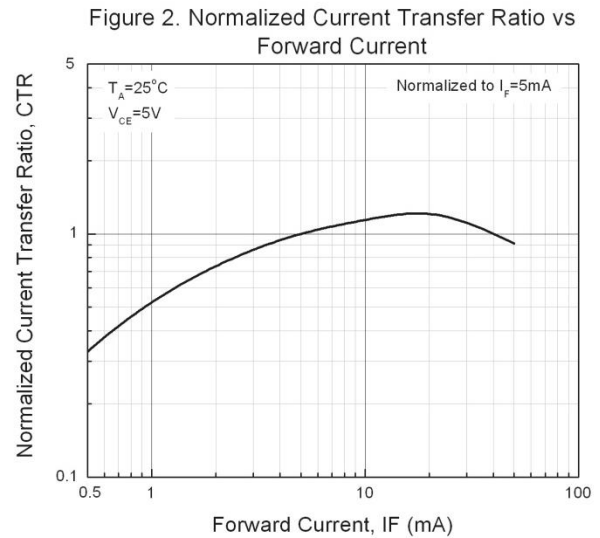
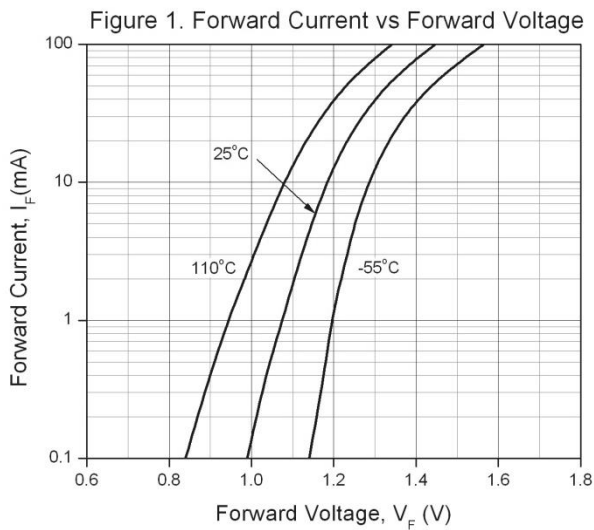
Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I _{CEO}	-	-	100	nA	V _{CE} = 20V, I _F = 0mA
Collector-Emitter breakdown voltage	BV _{CEO}	80	-	-	V	I _C = 0.1mA
Emitter-Collector breakdown voltage	BV _{ECO}	7	-	-	V	I _E = 0.1mA

Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL817	50	-	600	%	I _F = 5mA, V _{CE} = 5V
	EL817A	80	-	160		
	EL817B	130	-	260		
	EL817C	200	-	400		
	EL817D	300	-	600		
	EL817X	100	-	200		
	EL817Y	150	-	300		
Collector-Emitter saturation voltage	V _{CE(sat)}	-	0.1	0.2	V	I _F = 20mA, I _C = 1mA
Isolation resistance	R _{IO}	5×10 ¹⁰	-	-	Ω	V _{IO} = 500Vdc, 40~60% R.H.
Floating capacitance	C _{IO}	-	0.6	1.0	pF	V _{IO} = 0, f = 1MHz
Cut-off frequency	f _c	-	80	-	kHz	V _{CE} = 5V, I _C = 2mA, R _L = 100Ω, -3dB
Rise time	t _r	-	6	18	μs	V _{CE} = 2V, I _C = 2mA, R _L = 100Ω
Fall time	t _f	-	8	18	μs	

* Typical values at T_a = 25°C

Typical Electro-Optical Characteristics Curves



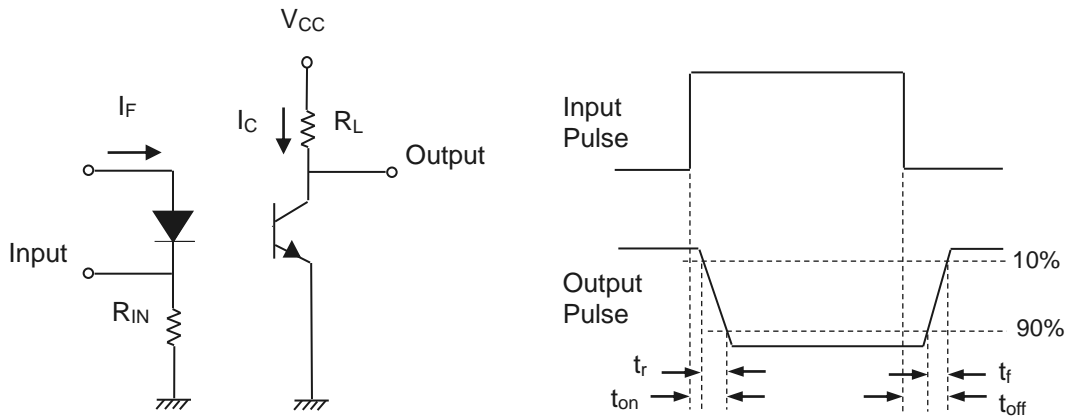


Figure 7. Switching Time Test Circuit & Waveforms

EVERLIGHT

Order Information

Part Number

EL817X(Y)(Z)-FVG

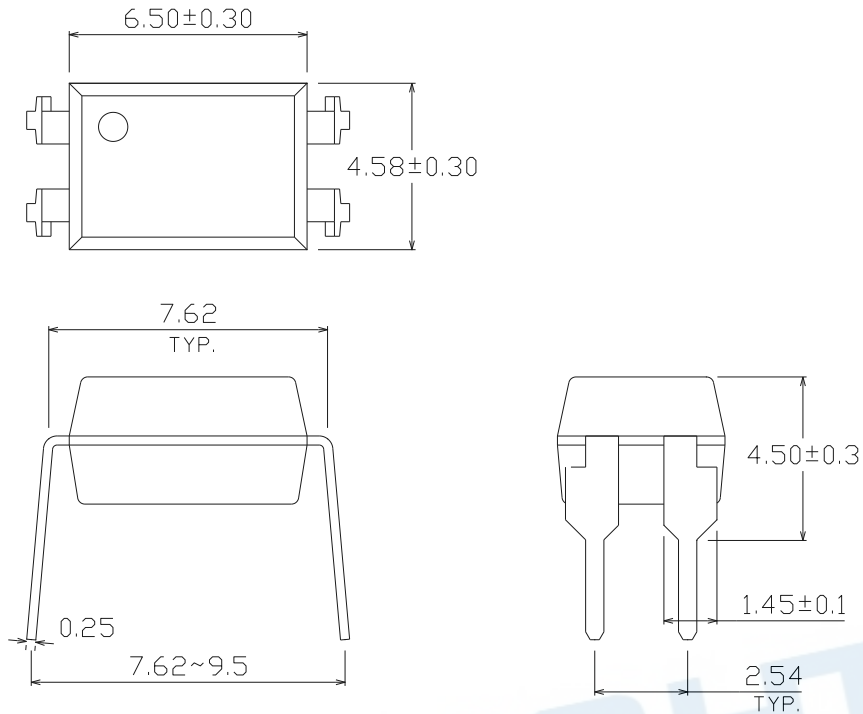
Note

- X = Lead form option (S1, S2, M or none)
- Y = CTR Rank (A, B, C, D, X, Y or none)
- Z = Tape and reel option (TU, TD or none)
- F = Lead frame option (F: Iron, None: copper)
- V = VDE safety (optional)
- G = Halogens free

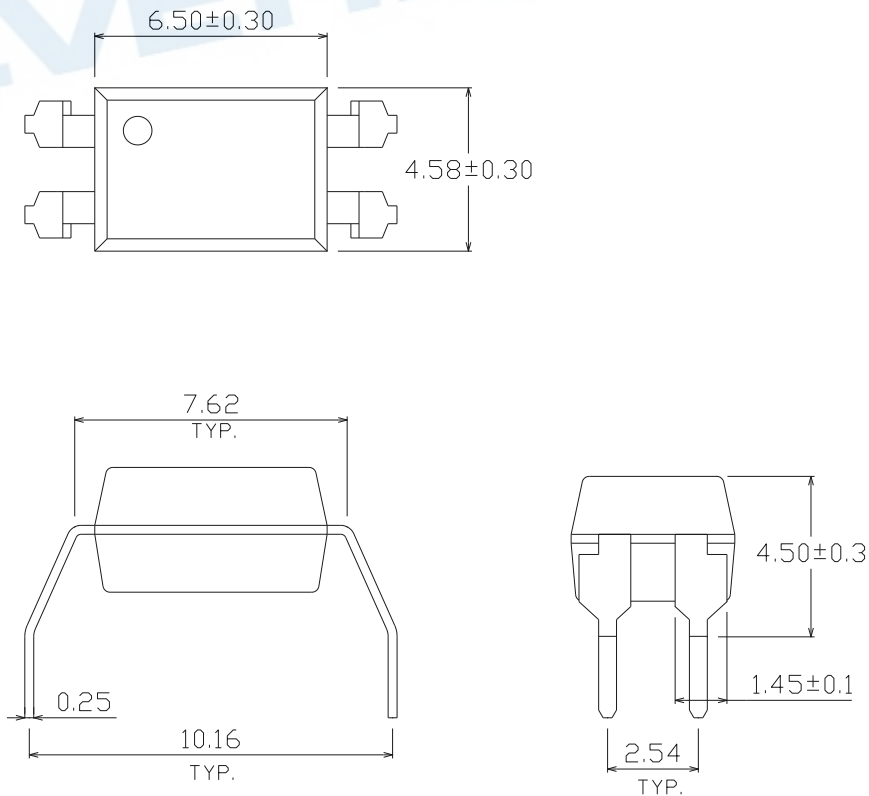
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

Package Dimension (Dimensions in mm)

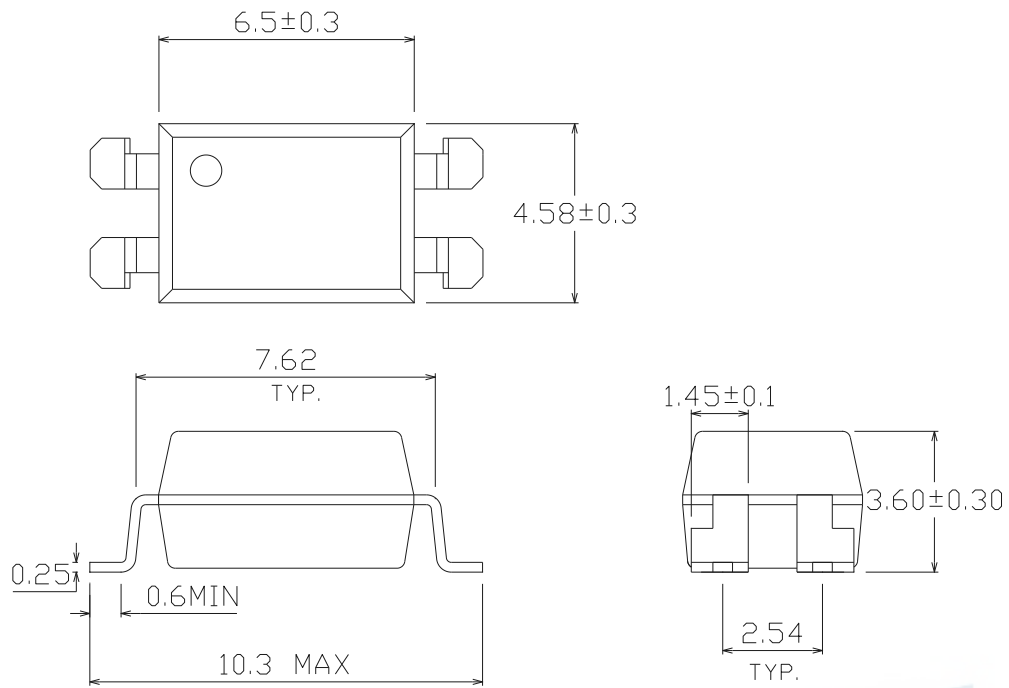
Standard DIP Type



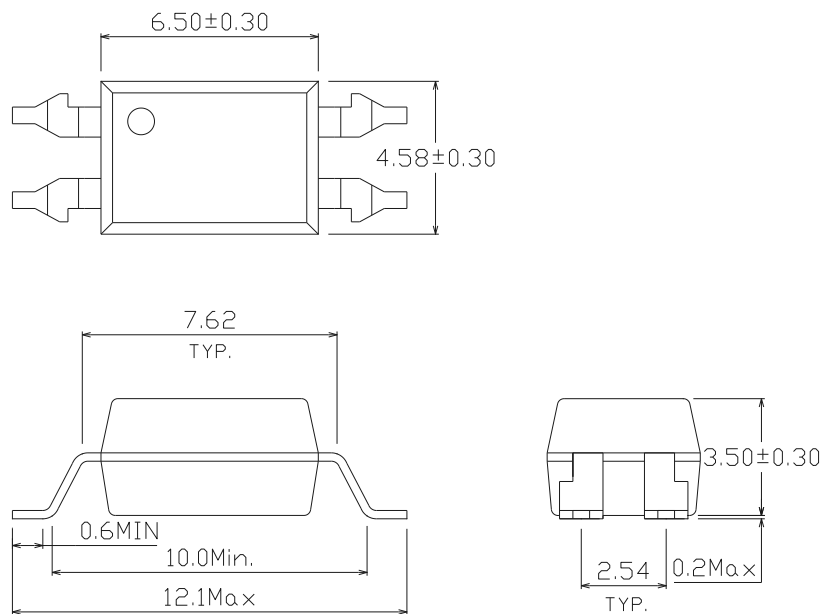
Option M Type



Option S1 Type

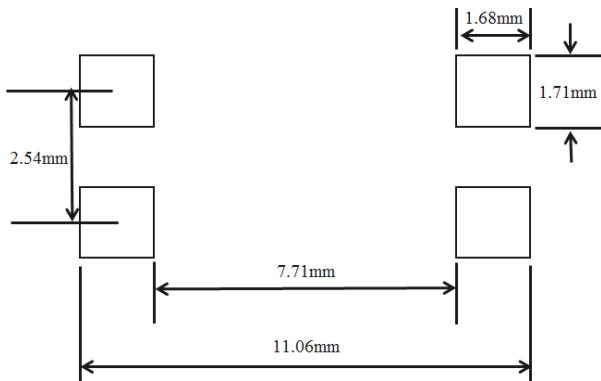


Option S2 Type

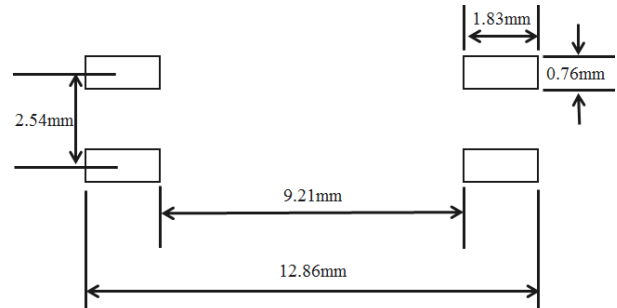


Recommended pad layout for surface mount leadform

For S1 option



For S2 option



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

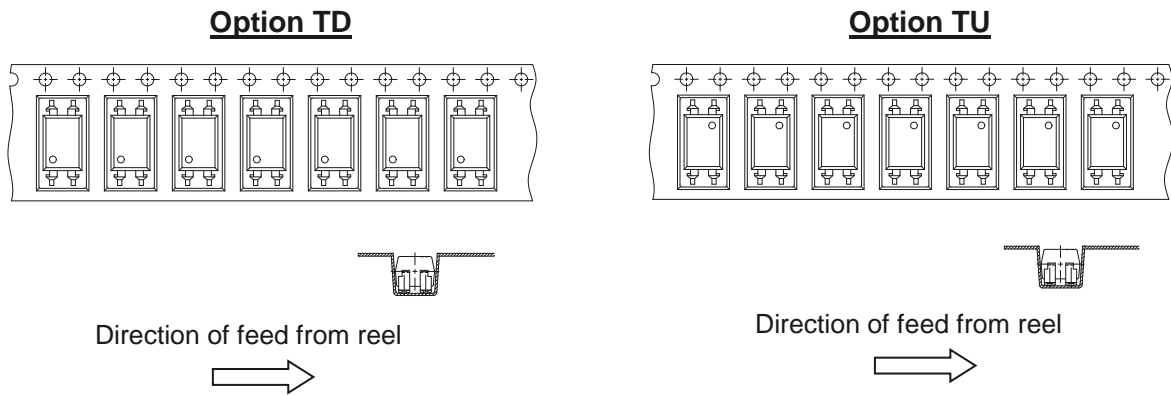
Device Marking



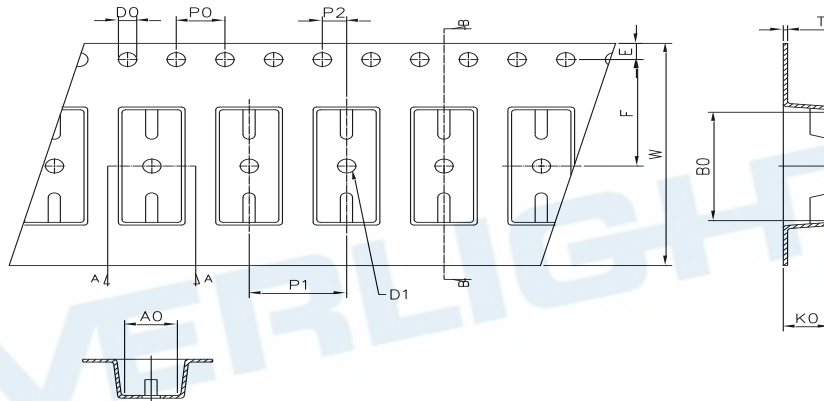
Notes

- EL denotes EVERLIGHT
- 817 denotes Device Number
- G denotes Green part
- R denotes CTR Rank (A, B, C, D, X, Y or none)
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code
- V denotes VDE (optional)

Tape & Reel Packing Specifications



Tape dimensions

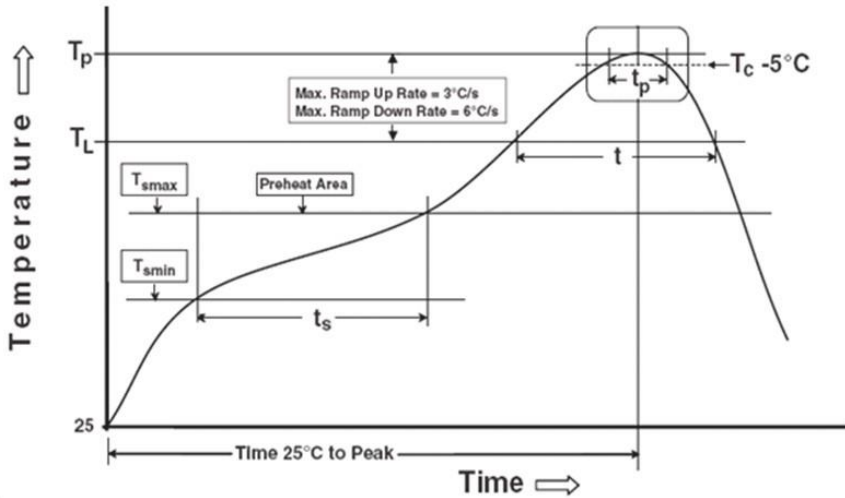


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

DISCLAIMER

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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